

Form Type	Distribute	Version	rsion 2.0 Ref		Ref	IPC 175.		2A Sectionals		s	Manufacturing Info/ Material Info		Subsectionals	D, A
		Supplier In												
Company Name	TE Connectivi	ty Request				Contact		1	Nelson	Cont	tact Title	Mg	r Global Account	s
Company	TE Connectivi		Document ID Response Date		2016-07-26		Contact Email		nelson.chan@te.com					
Unique ID			-											
Contact Phone	Number	+852-2738	8751											
Supplier	true					Legal S	tatement							
Acceptance														
Legal Statemen														
The information way modify exist	provided in this or ing purchase sp	document is bas ecifications or ex	ed upo disting	n reasonab contractual	or othe	ry of our s r agreem	suppliers. ents term	This in	formation is en TE Con	subje nectivi	ct to change. ty (or its affilia	Thi:	s information doe I companies) and	es not in any its customers.
	1	1.		T			duct							
Manufacturer Item number	5-1814832-1	832-1 Amount		1.124		Version		-	Iden		tity			
Manufacturer Item Name	SMA Str PCB Skt GZD	Weight Uo	Weight Uom		g		Mfr Site			Authority				
Date		UOM	UOM Each											
EURoHS-0508	Product(s) me	Product(s) meets EU RoHS requirements by application of the selected exemption(s)												
ChinaRoHS- 0508	Product(s) is I Products	NOT eligible for	markin	g with the e	code u	nder Chir	na's Meas	ures fo	r Administra	ition o	f the control o	of po	ollution by Electro	nic Information
EUREACH-1215	REACH Cand	idate Substance	s of Ve	ery High Co	ncern A	RE NOT	Containe	d in the	Product Ab	ove th	ne Limits per t	he I	Definition within F	REACH
					Man	ufacturin	ng Inform	ation						
J-STD-020 MSL Rating		Max Total Wave Time	Max Total a Vave Time		Ra		Rate		Wav Addi		e itional Info			
Classification Temp			Max Wave Solder Time		10.0		Ramp Down Rate		Psi R Reflo		Rating ow			
Max Time Within 5		Psl Rating Wave					Package Designator		Size			0.0		
Time Above 217	7	Reflow					Preheat Max Temp		Termi Alloy		ninal Base	NAC		
Preheat Duration		bulk Solde	bulk Solder Termination		NAC		Nbr or Reflow Cycles		Term Plati		inal NAC		.C	
Preheat Min		Nbr of	'11	0		Component			Shap			NAC		
Temp		Instances		Ĺ		Temp S								
1		1	T		1		Disclosur		T					
Sub- Item/Material/ Substance	Level	Name		stance Substance CAS		nce Substar Concen			Quantity		Mass per Ur	nit	UOM	Exemption
Material	1	Gold plated							1.0		0.092		g	
Substance	2	Gold	Supplier		7440-5	57-5	100.0		1.0		0.092		g	
Material	1	INSULATOR							1.0		0.189		g	
Substance	2	Ethene, 1,1,2,2- tetrafluoro-, homopolymer	Supp	Supplier		9002-84-0		1.0		0.189			g	
Material	1	BODY	1						1.0		0.729		g	
Substance	2	Lead		l/Lead pounds	7439-92-1		0.0020		1.0		1.458E-5		g	
Substance	2	Aluminum	Supp	olier	7429-9	7429-90-5		4.07		1.0		0.0296703		
Substance	2	Contains No Reportable TE5081-2 Substances	Supp	olier	TE5081-2- 1212		0.097		1.0		7.0713E-4		g	
Substance	2	Copper	Supp	olier	7440-5	7440-50-8			1.0		1.8954E-4		g	
Substance	2	Zinc	Supp	olier	7440-6	7440-66-6			1.0		0.698382		g	
Substance	2	Iron oxide	Supp	olier 133		37-2 0.005			1.0		3.645E-5		g	
Material	1	CONTACT	1					1.0			0.111		g	
	2	Copper		Supplier		8-08	87.84	1.0			0.0975024		g	
Substance	2	Contains No Reportable TE5081-2 Substances	Supp	olier	TE508 1212	1-2-	0.01		1.0		1.11E-5		g	
	2	Zinc	Supp	upplier 7		66-6	4.3	1.0			0.004773		g	
Substance	2	Tin	Supp	olier	7440-31-5		4.1		1.0		0.004551		g	

Substance	2	Lead	Lead/Lead Compounds	7439-92-1	3.75	1.0	0.0041625		6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Material	1	Nickel plated				1.0	0.0030	g	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	0.0030	g	